

National Informatics Center Ministry of Electronics & Information Technology

Application for Smart Card Product Certification

MICRO MODULE SMART CARD INLAY

1	Name & Address of Applicant/ Supplier (Also mention Tel, Fax, email)	
2	Name & Address of Manufacturer (If different from above) (Also mention, Tel, Fax, email)	
3	Description of the Smart Card Product :- a. Nomenclature/Model No. b. Version & Year of release c. Product Description Reference	
4	Applicable Specification (As per which product needs to be tested and certified)	<p>As per the following Specifications:</p> <p>1. SCOSTA specification V 1.2b : March 2002 including all addendums and errata including the latest dated 1st July 2006 <input type="radio"/></p> <p style="text-align: center;">OR</p> <p>SCOSTA CL V1.2: July 06 including all addendums and errata including the July 23rd, 2007. <input type="radio"/></p> <p>2. Certificate/Declaration of conformity with : ISO7816 Part-1,2,3 <input type="radio"/> / ISO 14443 Part-1,2,3 <input type="radio"/> (as required)</p> <p>3. Certificate of chip security assurance Common Criterion EAL4 issued from recognized CCRA Schemes and details present in the certified product at www.commoncriteriaportal.org <input type="radio"/> or EMVCO compliance certificate and details available at the EMVCO approved product list (Chip manufacturer approved product). <input type="radio"/></p> <p>4. Certificate/Declaration for ISO 9001/CMMI level 3 or above, Certification for manufacturing facility for following as applicable: i) Manufacturing of Smart Card(implantation/embedding). <input type="radio"/> ii) Manufacturing of microcontroller module. <input type="radio"/> iii) Manufacturing of microcontroller inlays. <input type="radio"/></p> <p>5. ISO 9001/CMMI level 3 or above, certificate of the supplier/ <input type="checkbox"/> client facility.</p> <p>6. Certificate of Incorporation in India <input type="checkbox"/></p> <p>7. "Certificate of registration" for brand name of product submitted <input type="checkbox"/></p>

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		<p>8. In-case of Flash memory based product</p> <p>a) Flash programming decleration certificate submitte</p> <p>b) Chip ID Tool (Hardware and software) to allow identification of the chip in the smart card submitted <input type="checkbox"/></p>
5	Specify type of testing service required [Tick as appropriate]	<p>Hard Mask (Single phase testing)</p> <p>Soft Mask (Two phase testing)</p>
6	Enclosures for performing testing and certification of the product submitted [As per enclosures given in Page 6 of this document]	<p>a.</p> <p>b.</p> <p>c.</p> <p>d.</p> <p>e.</p> <p>f.</p> <p>g.</p> <p>h.</p>
7	Fee details as submitted [Indicate amount and the DD details]	
8	Application filled in by	
9	Date	

Declaration :

. I will abide by all the Rules and Procedures of the Certification Body .

. I agree with the terms & conditions of the Certification body .

. I agree with the schedule of Charges of certification.

. I agree with the certification agreement.

(Authorised Signatory)

Product Information sheet

PLEASE SPECIFY EACH OF THE FOLLOWING

1. Product has following Microprocessor Chip with type of interface

a) Type of Microprocessor Chip

- Soft Mask chip (in case of two phase testing)
- Hard Mask Chip
- Other(please specify):

b) Type of Interface : - Contact interface Contactless interface

2. Product details under which , product will be brought into market

Name:	
Make:	
Model:	

3. ISO 7816-1, 7816-2, 7816-3 standards Compliance or ISO 14443-1,2,3 (As applicable)

Tested and certified (copy of certificate from lab/ issuing agency attached).

Initiated the process to get the same

4. Protocol Supported

- T=0 T=CL(A)
- T=1 T=CL(B)
- Both T=0 & T=1
- Any Other (please specify)

5. ATR Details

	Total Length (bytes) :	
	Byte by Byte description : (May be attached as separated documents)	

6. Chip profile (Details to be Provided for the HARD MASKED chip, which is submitted /shall be submitted for testing and with which the final product shall be brought into market)

Manufacturer's Name and Contact address	
Model No	
Production date	
Batch No	
Chip Nos. of all products submitted for testing	
Architectural Details Size of: RAM ROM / Read Only Locked Flash EEPROM/Rewritable Flash	
Chip supports the method for making chip number available to OS (Yes/No)	
Field Length of the Chip Number (number of Bytes)	
Byte by Byte description : (May be attached as separated documents)	

7. Operating system profile

Name	
Version No & Date of Release :	
Developer's Name and address:	

Size of OS	In terms of bytes occupied by: ROM/Read Only Locked Flash Space used by OS in EEPROM / Rewritable Flash for interfacing and files used by OS (internal EF)
Is OS tested and certified for ISO 7816-4-8-9 certified	<input type="radio"/> YES (Attach a copy of the same) <input type="radio"/> NO
Is OS tested and Certified for ISO 14443 part 1,2.,3 for Scosta CL or Contactless.	<input type="radio"/> YES (Attach a copy of the same) <input type="radio"/> NO

OS Supported List of commands:

	Are additional than specified in SCOSTA / SCOSTACL standard(as applicable) (including Errata)
	Are less than those specified in SCOSTA / SCOSTACL standard(as applicable) (Mention why)
	Are interpreted differently than those specified in SCOSTA / SCOSTACL (as applicable) (Mention why)

OS Properties	
DF Size(Max & Min)	
DF levels supported from top in hierarchy	
Max No of DF`s supported within a DF or MF	
Max No of EF`s supported within a DF or MF	
Max & Min Transparent EF size in bytes	
No of records supported in fixed record EF(Max & Min)	
Records supported in variable length record EF(Max & Min)	
No of records supported in cyclic EF(Max & Min)	
Record Length in all above three cases (Max & Min)	
Max No of Keys supported per DF	
Max No of security environments supported per DF	

Table 1

Max key length(bytes)	
Max reference data length (bytes)	
Max SE length (bytes)	
Max length of random No generated	
Random No generation by (OS/ Chip Hardware)	
3 DES support (YES/ NO)	
Data object #46 returns unique chip SI. No. (YES/ NO)	
Any other crypto algorithm supported (YES/ NO if yes then give details)	
Secure messaging supported (YES/ NO)	
Anti-tearing available (YES/NO)	
Maximum I/O Buffer Memory size	

Enclosures to be submitted along with the application:

1. Operating System Manual and Chip Technical Manual.
2. Other documents/ certificates as mentioned above and in the criteria.
3. Card Reading device - 03 Nos.
4. No. of cards /Inlays / Microcontroller module
 - a. Soft Mask Chip : 10 numbers to be submitted (in case initialization command is provided) else submit 50 cards . Undertaking is required to ensure that initialization command is not there in case of Hard Mask Cards as given in Annexure-I. After testing, the indenter shall take the corrective action and resubmit the 50 hard mask cards for testing. Charges for one cycle of regression testing are included in the initial testing Fee.
 - b. Hard Mask Chip : 50 numbers to be submitted. No provision for regression testing is made here. However after testing, the client may take the corrective action and resubmit fresh application for testing along with the same nos. of cards & test fee.
5. Certificate of Incorporation in India.
6. "Certificate of registration" for Brand of Product.
7. The Products submitted by the Applicants should have Applicant Name, it's Brand Name and the Chip Serial Number duly printed on the sample Form Factor itself through dye sublimation printing in case of card & other kind of printing in case of inlays.
8. The samples submitted must have a Form Factor in case of module/ Inlays such that the testing can be done conveniently.

9. The supplier / applicant shall provide the Chip ID Tool (hardware and software) to allow identification of the chip in the smart card submitted for certification, in case of flash based product.
10. The 10 Soft Masked samples submitted should have command for initializing the card's file system.
11. The document ISO 9001/ CMMI level 3 or above should clearly cover the scope of manufacturer / supplier of the product samples submitted. In case of CMMI, Published Appraisal Report need to be submitted.
12. Details in Column 6 of product information sheet should be provided for the Microcontroller Chip to be used for final Hard Masking and embedded in the final product as mentioned in the 3rd column of the application.
13. In case of flash based product a "Flash Programming Declaration Certificate" shall be submitted by the supplier/applicant from chip vendor declaring that the Operating System has been loaded in the Flash Memory chip at wafer level in the chip manufacturer's facility and that it has been locked at that facility in a way that it cannot be altered, modified, erased or deleted either selectively or wholly. The format of the certificate is given in SCSPC-06-10.
14. The applicant should submit from chip vendor EAL4+(or Higher) Common Criteria Certificate along with Security Target of Evaluation of the Boot loader/Flash Loader/Start Program / Boot Program under the Common Criteria Certificate. The Common Criteria Certificate must display BSI-CC-PP-0035-2007 / BSI-CC-PP-0084-2014 (or newer) Protection Profile in case of flash based products

NOTE:

- **All pages of the application, product information sheet and all attached documents submitted by the applicant should be properly stamped and signed .**
- **The application should be filled as per the format given & printout of same need to be attached while submitting the application .**

ANNEXURE-I

UNDERTAKING OF INITIALIZATION COMMAND FOR HARD MASKED CARDS

Mr. / Mrs. / Ms. .

of

(Name of Organization) do hereby declare that the initialization command provided along with soft mask cards in the first phase of two phase Testing ,which is mentioned below , hasbeen removed from the operating System before preparing the final mask for hard masking .

initialization command :-

CLA=

INS=

P1=

P2=

Lc=

Le=

Dated :

(Signature)